

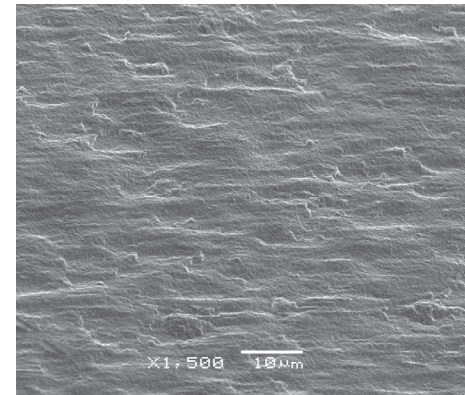
High temperature stability electrodeposited copper foil.

**Applications:**

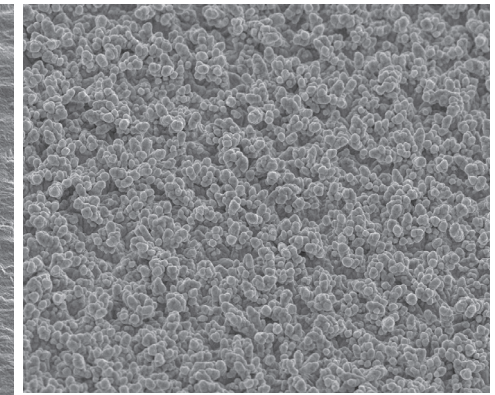
- PCB outer layers
- PCB inner layers

**Features:**

- IPC Grade III
- Treatment on matte side of foil
- High temperature lamination compatible



Untreated Drum Side  
H oz. /18 μm (1500x)



Treated Matte Side  
H oz. /18 μm (1500x)

**Typical Values:**

Attribute		Unit	Value					Reference
Thickness Designation			T	H	1	2	3	IPC-4562, 1.2.5.1 Table 1-1; IPC-TM-650-2.2.12
Nominal Thickness		μm	12	18	35	70	103	
		oz.	3/8	1/2	1	2	3	
Area Weight		g/m <sup>2</sup>	106.8	152.5	305	610	915	
		g/254 in <sup>2</sup>	17.5	25	50	100	150	
		oz./ft <sup>2</sup>	0.375	0.5	1	2	3	
Roughness	Drum Side Ra	μm	0.25					IPC-TM-650-2.2.17
		μ"	10					
	Matte Side Rz	μm	5.1	6.4	10.2	15.4		
		μ"	200	250	400	606		
Tensile	Ambient	Kg/mm <sup>2</sup>	42	39	37	35	IPC-TM-650-2.4.18	
		Kpsi	60	55	53	49		
	180°C	Kg/mm <sup>2</sup>	21					
		Kpsi	30					
Elongation	Ambient	%	6	8	15	20	25	
	180°C	%	8	8	8	8	7	
Peel Strength* (Matte/Treated Side)	Cond. B	Kg/cm	0.89	0.98	1.16	1.25	1.50	IPC-TM-650-2.4.8
		Lbs/in	5.0	5.5	6.5	7	8.4	

\* Peel strength measured on 170°C Tg Epoxy

Information in this document is believed to be accurate and reliable and is for informational purpose only. This data sheet does not create any warranties, expressed or implied, as to the fitness for any particular purpose or use. The Denkai America Inc. name and logo are registered trademarks of Nippon Denkai, Ltd. © 2020, Denkai America Inc. All rights reserved. Rev May 4, 2020